

ABSTRACT

A multilayer wiring board comprising at least two double-sided wiring boards which comprises an insulating substrate and conductive metal wiring patterns on both
5 surfaces of the insulating substrate. The wiring patterns on the insulating substrate are connected through a conductive metal in a through hole through the insulating substrate. The double-sided wiring boards are electrically connected by joining of low-melting conductive metal layers on connection
10 terminals at the mating surfaces of the double-sided wiring boards. The at least two double-sided wiring boards are bonded by means of a polyimide adhesive resin that is selectively applied by screen printing on the double-sided wiring boards other than on the connection terminals. The wiring boards are
15 reliably laminated, and the multilayer wiring board has a reliable electrical connection between the wiring boards.